



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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485 Series Fuse



Agency Approvals

Agency	Agency File Number	Ampere Rating
	E10480	1A - 3.15A
	29862	1A - 3.15A

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	60 seconds, Maximum

Description

The 485 Nano² Fuse Series is a small, fast-acting, surface mount ceramic fuse rated at a remarkable 600VDC at its small size and with 100A breaking capacity. It is primarily designed for circuit protection in high energy applications. This product is fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.

Features

- Fast-Acting / Surface mount high fuse for voltage (up to 600VDC) applications.
- Fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.
- Relatively high breaking capacity at 100A.
- RoHS compliant / Halogen Free
- Rating – 1 - 3.15 Amperes.

Applications

- PC server and Telecom systems
- LCD TV inverter boards DC input protection
- Uninterruptible Power Supply (UPS) / 3-Phase Power Supplies
- 380VDC server / lighting in data center

Additional Information



[Datasheet](#)





[Resources](#)



[Samples](#)

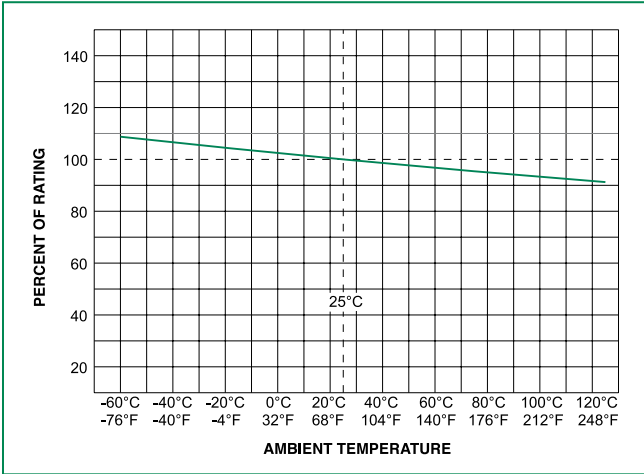
Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Agency Approvals	
							
1.00	001.	600	100A@600VDC, 100A@250VAC	0.264	0.3044	X	X
1.50	01.5	600		0.123	0.3917	X	X
2.00	002.	600		0.0744	0.8962	X	X
2.50	02.5	600		0.0583	1.4921	X	X
3.15	3.15	600		0.0395	3.304	X	X

Notes:

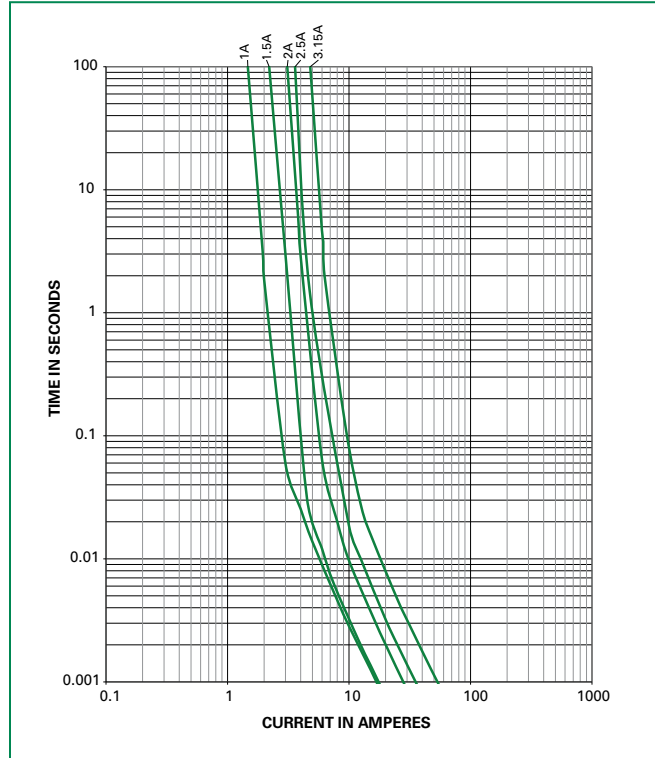
1. Cold resistance measured at less than 10% of rated current at 23°C.
2. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved.
3. I²t values stated for 8 msec opening time.

Temperature Re-rating Curve



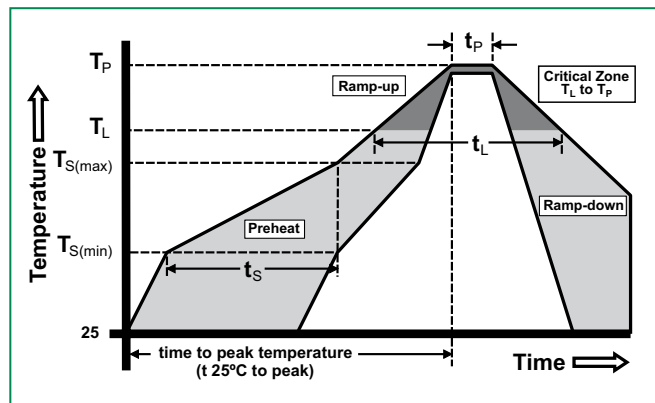
Note:
1. Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters - Reflow Soldering

Reflow Condition		Pb – Free Assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 ses
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

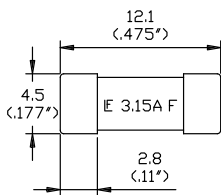


Product Characteristics

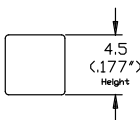
Material	Body: Ceramic Cap: Silver Plated Brass
Product Marking	Body: Brand Logo, Current Rating
Operating Temperature	-55°C to 125°C with proper derating
Moisture Sensitivity Level	Level 1 J-STD-020
Solderability	MIL-STD-202, Method 208
Insulation Resistance (after Opening)	MIL-STD-202, Method 302, Test Condition A (10,000 ohms, Minimum)

Thermal Shock	MIL-STD-202, Method 107, Test Condition B, 5 cycles, -65°C to 125°C, 15 minutes @ each extreme
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I: Deenergized. 100G's peak amplitude, sawtooth wave 6ms duration, 3 cycles XYZ+xyz = 18 shocks
Vibration	MIL-STD-202, Method 201: 0.03" amplitude, 10-55 Hz in 1 min. 2 hrs. each XYZ=6hrs
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles
Salt Spray	MIL-STD-202, Method 101, Test Condition B (48hrs)
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B (10 sec at 260°C)

Dimensions

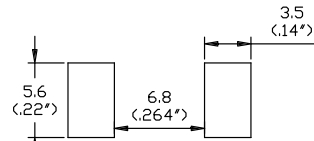


TOP VIEW



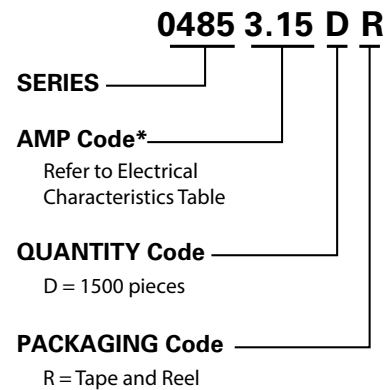
END CAP

Recommended Pad Layout



REFLOW SOLDER

Part Numbering System



***Example**
3.15 amp is 04853.15DR

Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Option Code
24mm Tape and Reel	EIA-RS 481-1, (IEC 286, Part 3)	1500	DR